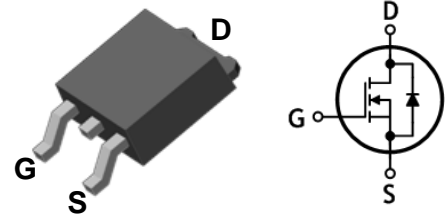


N-Channel Super Junction MOSFET

Features

- Drain-Source voltage: $V_{DS}=700V$ (@ $T_J=150^\circ C$)
- Low drain-source On resistance: $R_{DS(on)}=0.38\Omega$ (Max.)
- Ultra low gate charge: $Q_g=20nC$ (Typ.)
- RoHS compliant device
- 100% avalanche tested

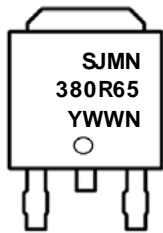


Ordering Information

Part Number	Marking	Package
SJMN380R65D	SJMN380R65	TO-252

TO-252

Marking Information



Column 1, 2: Device Code
 Column 3: Production Information
 e.g.) YWWN
 -. YWW: Date Code (year, week)
 -. N: Management Code

Absolute maximum ratings ($T_C=25^\circ C$ unless otherwise noted)

Characteristic	Symbol	Rating	Unit	
Drain-source voltage	V_{DSS}	650	V	
Gate-source voltage	V_{GSS}	± 30	V	
Drain current (DC) (Note 1)	I_D	$T_C=25^\circ C$	11	A
		$T_C=100^\circ C$	7	A
Drain current (Pulsed) (Note 1)	I_{DM}	44	A	
Single pulsed avalanche energy (Note 2)	E_{AS}	135	mJ	
Repetitive avalanche current (Note 1)	I_{AR}	5	A	
Repetitive avalanche energy (Note 1)	E_{AR}	7.6	mJ	
Power dissipation	P_D	76	W	
Diode dv/dt ruggedness (Note 3)	dv/dt	15	V/ns	
MOSFET dv/dt ruggedness (Note 4)	dv/dt	50	V/ns	
Junction temperature	T_J	150	$^\circ C$	
Storage temperature range	T_{stg}	-55-150	$^\circ C$	

Thermal Characteristics

Characteristic	Symbol	Rating	Unit
Thermal resistance, junction to case	$R_{th(j-c)}$	Max. 1.64	°C/W
Thermal resistance, junction to ambient	$R_{th(j-a)}$	Max. 62.5	

Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Drain-source breakdown voltage	BV_{DSS}	$I_D=250\mu\text{A}$, $V_{GS}=0$	650	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$I_D=250\mu\text{A}$, $V_{DS}=V_{GS}$	2	3	4	V
Drain-source cut-off current	I_{DSS}	$V_{DS}=650\text{V}$, $V_{GS}=0\text{V}$	-	-	1	μA
		$V_{DS}=650\text{V}$, $T_J=125^\circ\text{C}$	-	-	100	μA
Gate leakage current	I_{GSS}	$V_{DS}=0\text{V}$, $V_{GS}=\pm 30\text{V}$	-	-	± 100	nA
Drain-source on-resistance	$R_{DS(ON)}$	$V_{GS}=10\text{V}$, $I_D=5.5\text{A}$	-	0.31	0.38	Ω
Internal gate resistance	R_g	$f=1\text{MHz}$, Open drain	-	21	-	Ω
Input capacitance	C_{iss}	$V_{DS}=25\text{V}$, $V_{GS}=0\text{V}$, $f=1\text{MHz}$	-	787	-	pF
Output capacitance	C_{oss}		-	431	-	
Reverse transfer capacitance	C_{rss}		-	24	-	
Turn-on delay time (Note 5)	$t_{d(on)}$	$V_{DS}=350\text{V}$, $I_D=11\text{A}$, $R_G=25\Omega$	-	17	-	ns
Rise time (Note 5)	t_r		-	14	-	
Turn-off delay time (Note 5)	$t_{d(off)}$		-	40	-	
Fall time (Note 5)	t_f		-	5	-	
Total gate charge (Note 6)	Q_g	$V_{DS}=400\text{V}$, $V_{GS}=10\text{V}$, $I_D=7\text{A}$	-	20	-	nC
Gate-source charge (Note 6)	Q_{gs}		-	6.5	-	
Gate-drain charge (Note 6)	Q_{gd}		-	5	-	

Source-Drain Diode Ratings and Characteristics ($T_C=25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Source current (DC)	I_S	Integral reverse diode in the MOSFET	-	-	11	A
Source current (Pulsed)	I_{SM}		-	-	33	A
Forward voltage	V_{SD}	$V_{GS}=0\text{V}$, $I_S=11\text{A}$	-	-	1.2	V
Reverse recovery time (Note 5, 6)	t_{rr}	$I_S=11\text{A}$, $V_{GS}=0\text{V}$, $dI_S/dt=100\text{A}/\mu\text{s}$	-	326	-	ns
Reverse recovery charge (Note 5, 6)	Q_{rr}		-	2.8	-	μC

Note:

1. Calculated continuous current based on maximum allowable junction temperature
2. $L=10\text{mH}$, $I_{AS}=5\text{A}$, $V_{DD}=50\text{V}$, Starting $T_J=25^\circ\text{C}$
3. $I_S \leq 11\text{A}$, $V_{DS} \leq 400\text{V}$, $dI_S/dt \leq 100\text{A}/\mu\text{s}$, $T_J=25^\circ\text{C}$
4. $V_{DS} \leq 400\text{V}$, $I_S \leq 11\text{A}$
5. Guaranteed by design, not subject to production testing
6. Pulse test: Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$

Typical Electrical Characteristics Curves

Fig. 1 Typical Output Characteristics

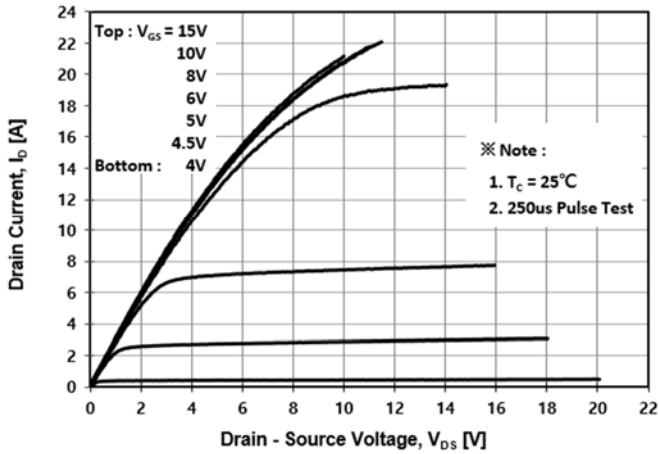


Fig. 2 Typical Transfer Characteristics

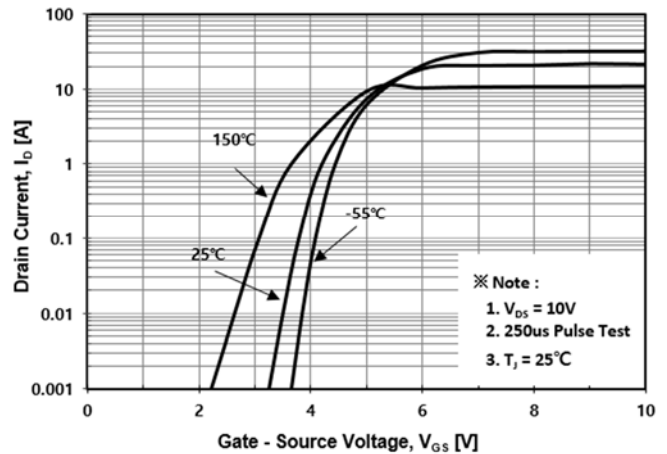


Fig.3 On-Resistance Variation with Drain Current and Gate Voltage

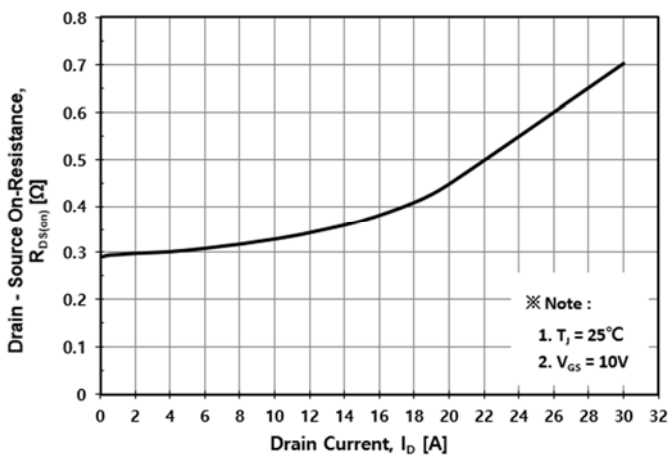


Fig. 4 Body Diode Forward Voltage Variation with Source Current

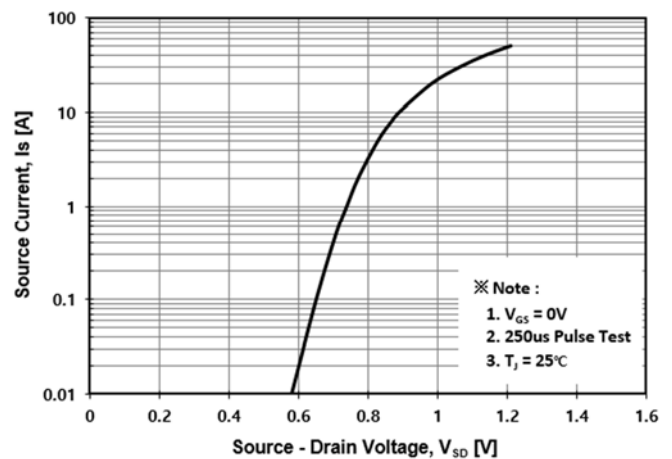


Fig. 5 Typical Capacitance Characteristics

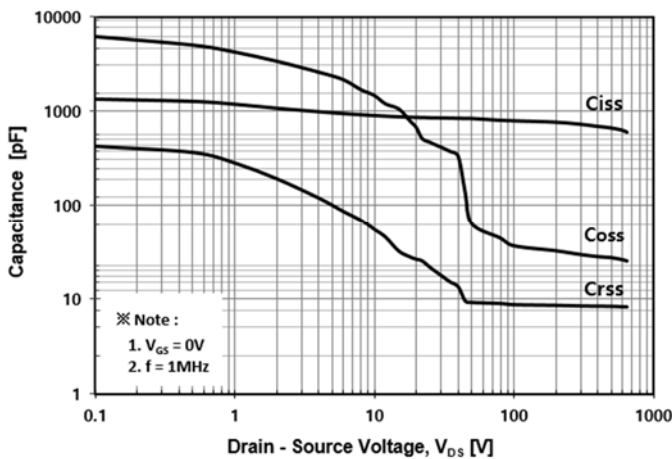


Fig. 6 Typical Total Gate Charge Characteristics

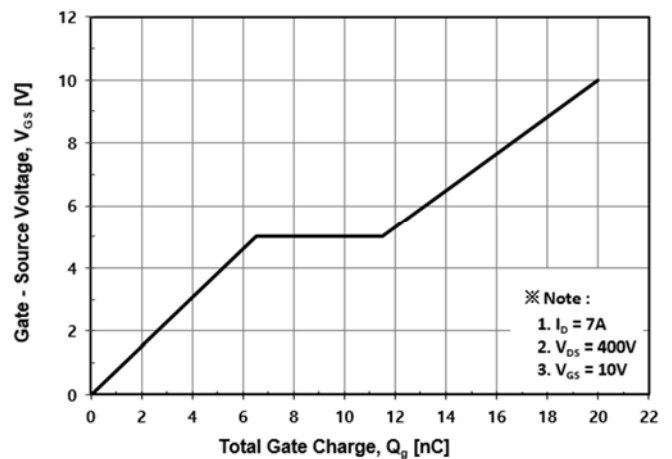


Fig. 7 Breakdown Voltage Variation vs. Temperature

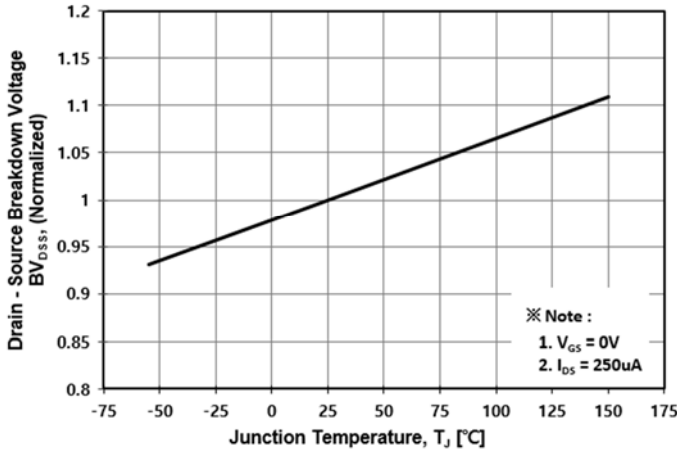


Fig. 8 On-Resistance Variation vs. Temperature

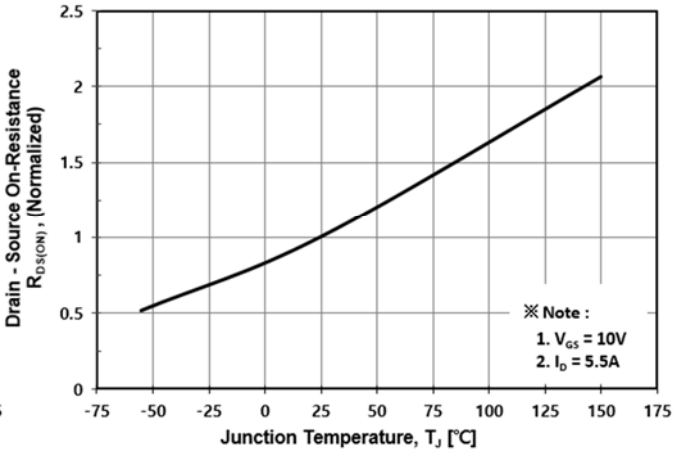


Fig. 9 Maximum Drain Current vs. Case Temperature

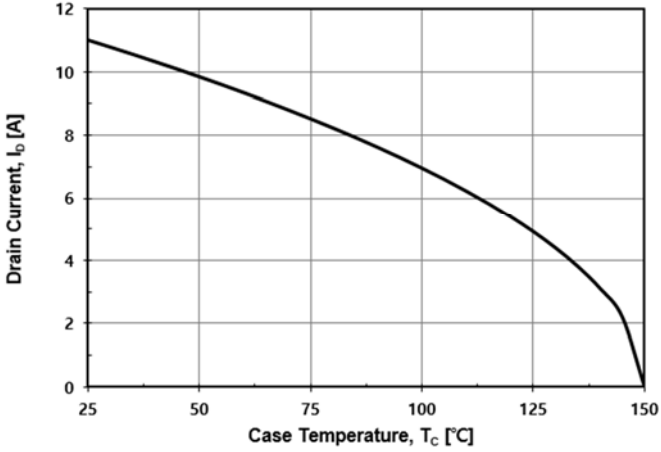


Fig. 10 Maximum Safe Operating Area

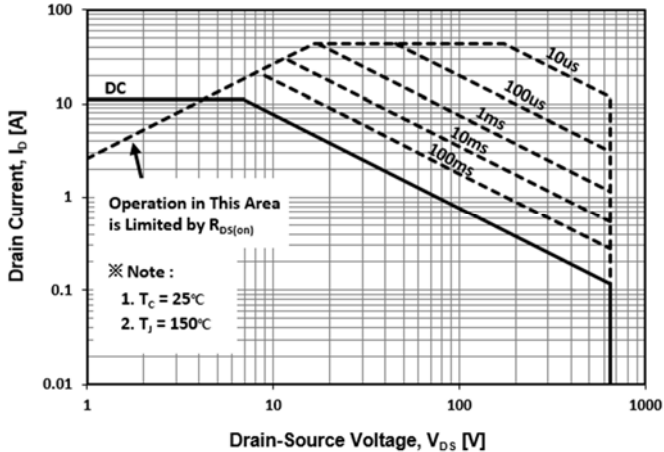


Fig. 11 Transient Thermal Impedance

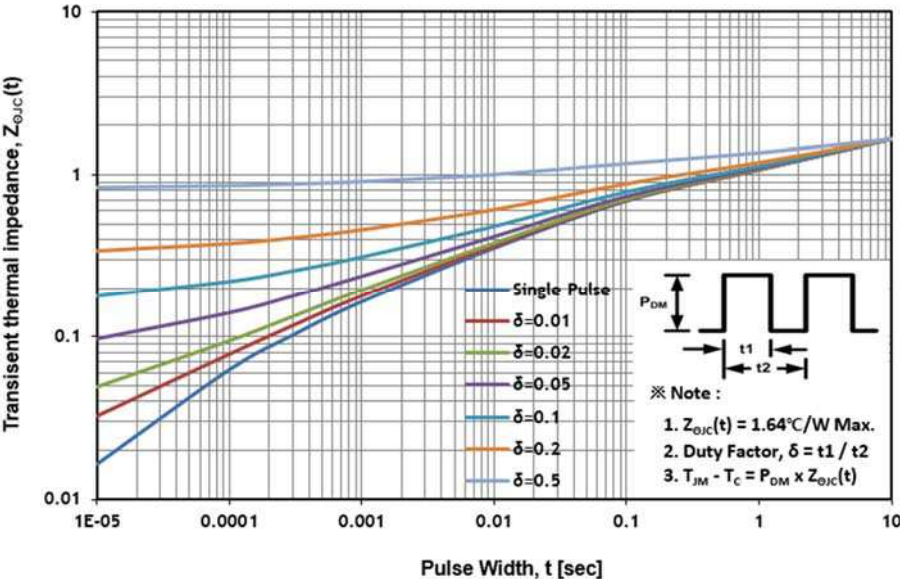


Fig. 12 Gate Charge Test Circuit & Waveform

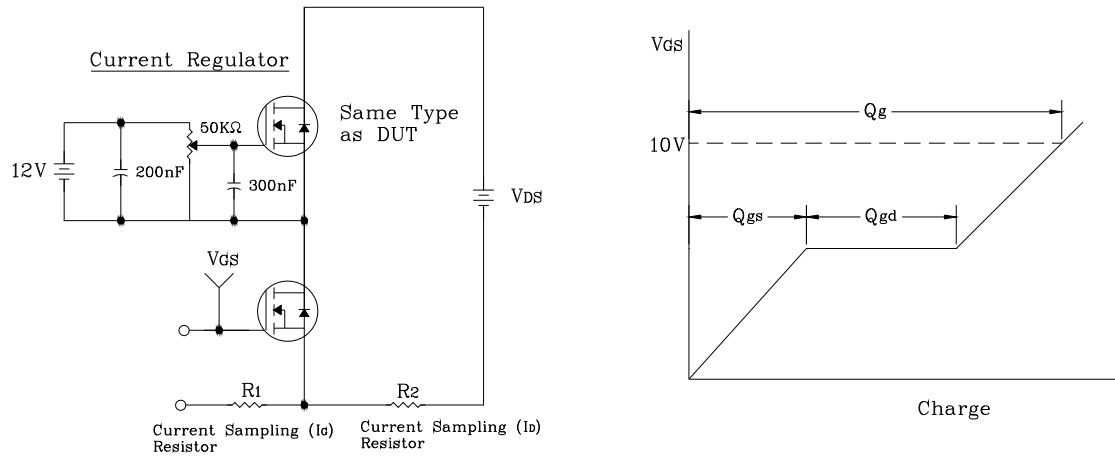


Fig. 13 Resistive Switching Test Circuit & Waveform

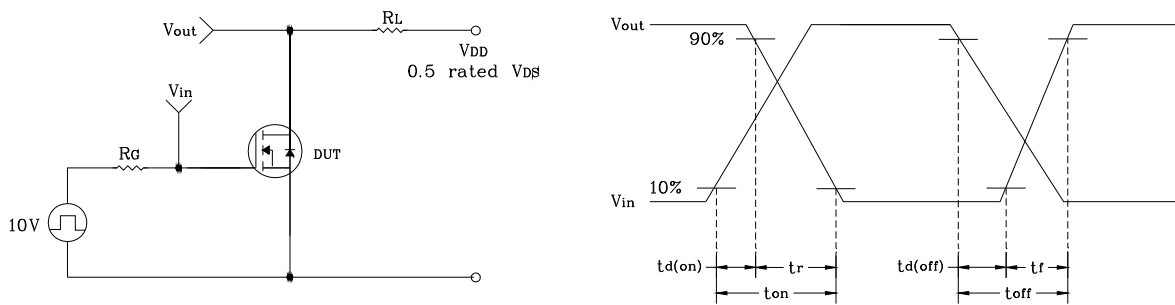


Fig. 14 E_{AS} Test Circuit & Waveform

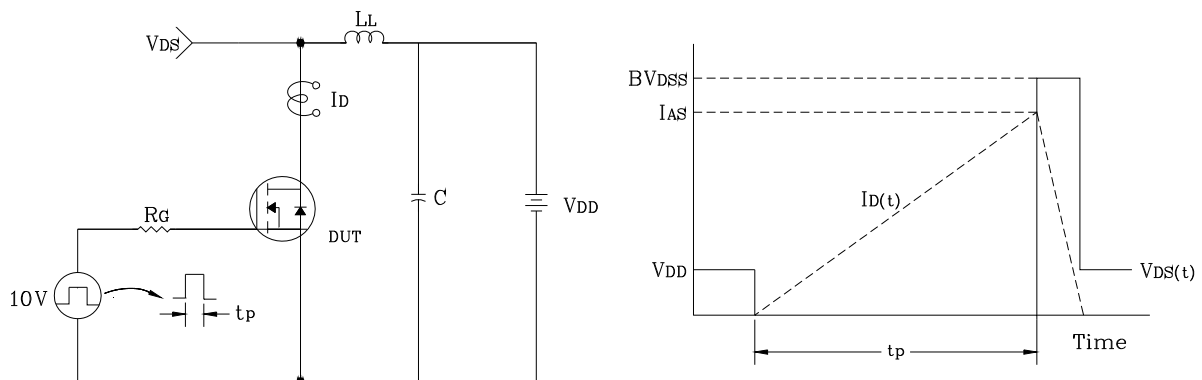
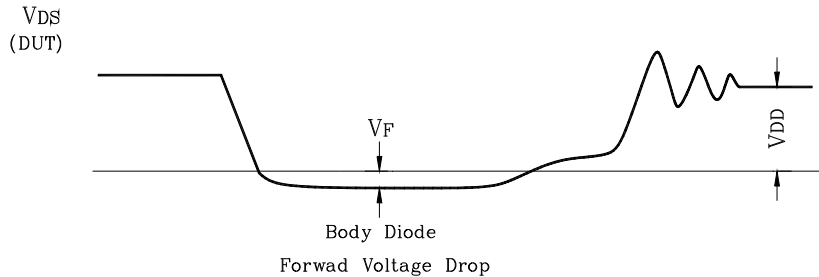
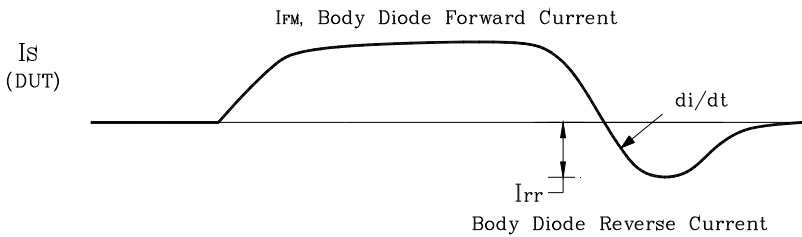
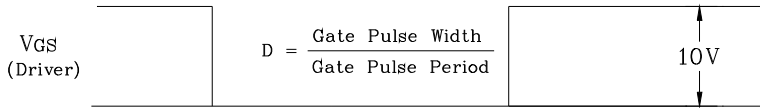
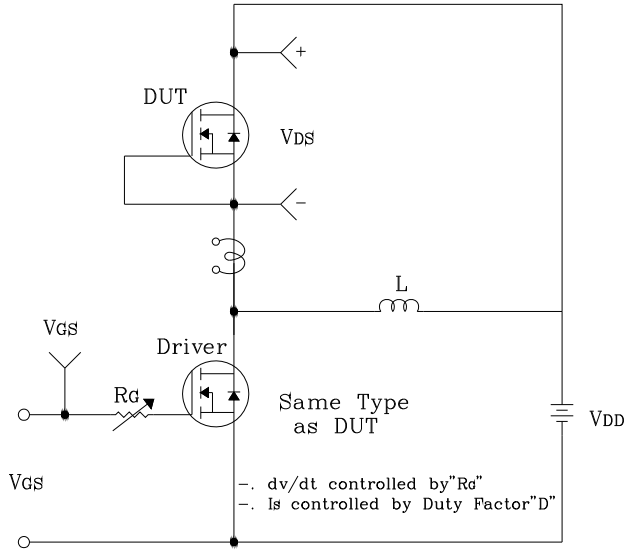
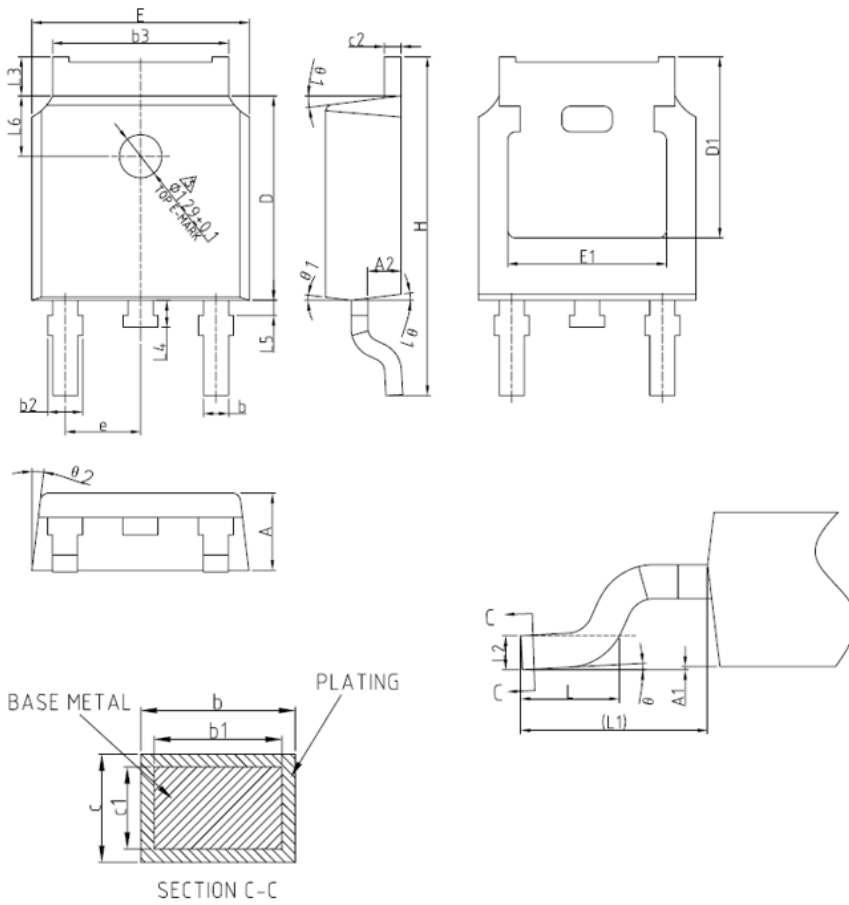


Fig. 15 Diode Reverse Recovery Time Test Circuit & Waveform



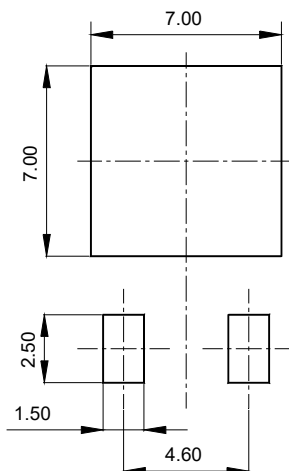
Package Outline Dimensions



COMMON DIMENSIONS
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	2.20	2.30	2.38
A1	0	-	0.10
A2	0.90	1.01	1.10
b	0.72	-	0.85
b1	0.71	0.76	0.81
b2	0.72	-	0.90
b3	5.13	5.33	5.46
c	0.47	-	0.60
c1	0.46	0.51	0.56
c2	0.47	-	0.60
D	6.00	6.10	6.20
D1	5.25	-	-
E	6.50	6.60	6.70
E1	4.70	-	-
e	2.186	2.286	2.386
H	9.80	10.10	10.40
L	1.40	1.50	1.70
L1		2.90REF	
L2		0.51BSC	
L3	0.90	-	1.25
L4	0.60	0.80	1.00
L5	0.15	-	0.75
L6		1.80REF	
θ	0°	-	8°
θ 1	5°	7°	9°
θ 2	5°	7°	9°

Recommended Land Pattern [unit: mm]



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